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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Anthony L. Coyle, et al.**
Serial No.: **09/992,387**
Filed: **11/16/2001**
For: **Flip-Chip On Film Assembly For Ball Grid Array Packages**

Docket No.: **TI-31794**
Examiner: **Lewis, M.**
Art Unit.: **2822**
Conf. No.: **7595**

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INFORMATION DISCLOSURE STATEMENT

November 6, 2002

Assistant Commissioner For Patents
Washington, DC 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(A)

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231.

Elizabeth Austin
Elizabeth Austin

11/6/2002
Date

Applicant wishes to bring to the attention of the Patent and Trademark Office the information noted on the enclosed PTO-1449. Copies of the listed references are enclosed.

If required, please charge the necessary fee of \$180 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,

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